# **Dual J-K Flip-Flop with Reset**High-Performance Silicon-Gate CMOS

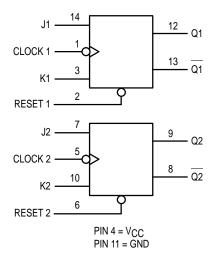
The MC74HC73 is identical in pinout to the LS73. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

Each flip flop is negative-edge clocked and has an active-low asynchronous reset.

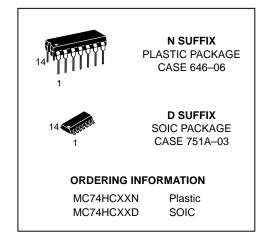
The MC74HC73 is identical in function to the HC107, but has a different pinout.

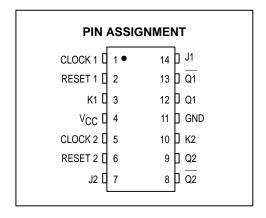
- Output Drive Capability: 10 LSTTL Loads
- · Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA
- · High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 92 FETs or 23 Equivalent Gates

#### **LOGIC DIAGRAM**



# **MC74HC73**





	Inputs	S		Out	outs
Reset	Clock	J	K	Ø	Q
L	Х	Χ	Χ	L	Н
Н	$\overline{}$	L	L	No Ch	nange
Н	~	L	Н	L	H
Н	~	Η	L	Н	L
Н	$\overline{}$	Н	Н	Tog	gle
Н	L	Χ	Χ	No Ch	nange
Н	Н	Χ	X	No Ch	nange
Н	_	Χ	Χ	No Ch	nange

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#### **MAXIMUM RATINGS\***

Symbol	Parameter	Value	Unit
VCC	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
V <sub>in</sub>	DC Input Voltage (Referenced to GND)	- 1.5 to V <sub>CC</sub> + 1.5	V
V <sub>out</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> + 0.5	V
l <sub>in</sub>	DC Input Current, per Pin	± 20	mA
l <sub>out</sub>	DC Output Current, per Pin	± 25	mA
Icc	DC Supply Current, V <sub>CC</sub> and GND Pins	± 50	mA
PD	Power Dissipation in Still Air Plastic DIP† SOIC Package†	750 500	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq$  ( $V_{in}$  or  $V_{out}$ )  $\leq$  VCC. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or VCC).

Unused outputs must be left open.

SOIC Package: - 7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
VCC	DC Supply Voltage (Referenced to GND)			6.0	٧
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)			Vcc	V
TA	Operating Temperature, All Package Types			+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time VCC (Figure 1) VCC VCC	; = 2.0 V ; = 4.5 V ; = 6.0 V	0 0 0	1000 500 400	ns

## DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Guaranteed Limit			
Symbol	Parameter	Test Conditions	v <sub>CC</sub>	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
VIH	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out}  \le 20 \mu\text{A}$	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V <sub>IL</sub>	Maximum Low–Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out}  \le 20 \mu\text{A}$	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	V
VOH	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20 \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{\text{in}} = V_{\text{IH}} \text{ or } V_{\text{IL}}   I_{\text{Out}}  \le 4.0 \text{ mA}$ $ I_{\text{Out}}  \le 5.2 \text{ mA}$	4.5 6.0	3.98 5.48	3.84 5.34	3.70 5.20	
VOL	Maximum Low–Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20 \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{\text{in}} = V_{\text{IH}} \text{ or } V_{\text{IL}}   I_{\text{out}}  \le 4.0 \text{ mA}$ $ I_{\text{out}}  \le 5.2 \text{ mA}$	4.5 6.0	0.26 0.26	0.33 0.33	0.40 0.40	
l <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	± 1.0	± 1.0	μΑ
lcc	Maximum Quiescent Supply Current (per Package)	V <sub>in</sub> = V <sub>CC</sub> or GND I <sub>out</sub> = 0 μA	6.0	4	40	80	μΑ

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

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<sup>\*</sup> Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

<sup>†</sup>Derating — Plastic DIP: - 10 mW/°C from 65° to 125°C

## AC ELECTRICAL CHARACTERISTICS ( $C_L = 50 \text{ pF}$ , Input $t_f = t_f = 6 \text{ ns}$ )

			Guaranteed Limit			
Symbol	Parameter	V <sub>CC</sub>	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
fmax	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 4)	2.0 4.5 6.0	6.0 30 35	4.8 24 28	4.0 20 24	MHz
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Clock to Q or Q (Figures 1 and 4)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Reset to Q or Q (Figures 2 and 4)	2.0 4.5 6.0	155 31 26	195 39 33	235 47 40	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 1 and 4)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance	_	10	10	10	pF

## NOTES:

- 1. For propagation delays with loads other than 50 pF, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).
- 2. Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Per Flip-Flop)*	35	pF

<sup>\*</sup> Used to determine the no–load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> V<sub>CC</sub><sup>2</sup>f + I<sub>CC</sub> V<sub>CC</sub>. For load considerations, see Chapter 2 of the Motorola High–Speed CMOS Data Book (DL129/D).

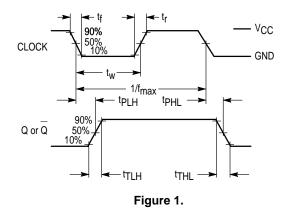
## **TIMING REQUIREMENTS** (Input $t_f = t_f = 6 \text{ ns}$ )

			Guaranteed Limit			
Symbol	Parameter	V <sub>CC</sub>	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
t <sub>su</sub>	Minimum Setup Time, J or K to Clock (Figure 3)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
th	Minimum Hold Time, Clock to J or K (Figure 3)	2.0 4.5 6.0	3 3 3	3 3 3	3 3 3	ns
t <sub>rec</sub>	Minimum Recovery Time, Reset Inactive to Clock (Figure 2)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
t <sub>W</sub>	Minimum Pulse Width, Clock (Figure 1)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t <sub>W</sub>	Minimum Pulse Width, Reset (Figure 2)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times (Figure 1)	2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

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## **SWITCHING WAVEFORMS**



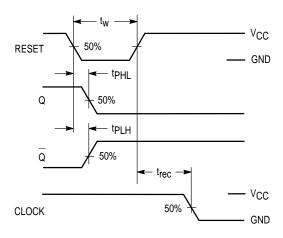


Figure 2.

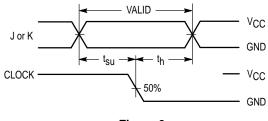
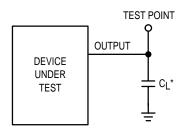


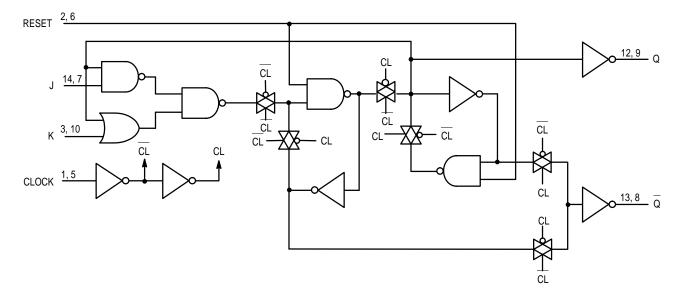
Figure 3.



\* Includes all probe and jig capacitance

Figure 4.

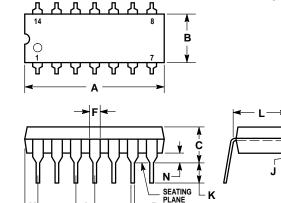
## **EXPANDED LOGIC DIAGRAM**



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#### **OUTLINE DIMENSIONS**

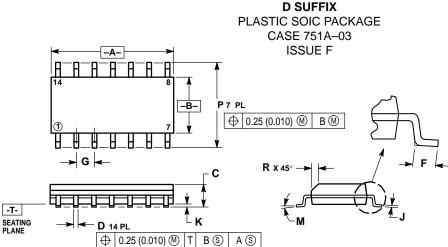
## N SUFFIX PLASTIC DIP PACKAGE CASE 646–06 ISSUE L



#### NOTES:

- LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH
- 4. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	19.56	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100	BSC	2.54	BSC	
Н	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.300	BSC	7.62 BSC		
М	0°	10°	0°	10°	
N	0.015	0.039	0.39	1.01	



#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

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**USA/EUROPE**: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036. 1–800–441–2447

MFAX: RMFAX0@email.sps.mot.com -TOUCHTONE (602) 244-6609 INTERNET: http://Design-NET.com

JAPAN: Nippon Motorola Ltd.; Tatsumi–SPD–JLDC, Toshikatsu Otsuki, 6F Seibu–Butsuryu–Center, 3–14–2 Tatsumi Koto–Ku, Tokyo 135, Japan. 03–3521–8315

**HONG KONG**: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park, 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852–26629298



